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NEWS 1		Web Page for STN Seminar Schedule - N. America
NEWS 2	DEC 01	ChemPort single article sales feature unavailable
NEWS 3	FEB 02	Simultaneous left and right truncation (SLART) added for CERAB, COMPUAB, ELCOM, and SOLIDSTATE
NEWS 4	FEB 02	GENBANK enhanced with SET PLURALS and SET SPELLING
NEWS 5	FEB 06	Patent sequence location (PSL) data added to USGENE
NEWS 6	FEB 10	COMPENDEX reloaded and enhanced
NEWS 7	FEB 11	WTEXTILES reloaded and enhanced
NEWS 8	FEB 19	New patent-examiner citations in 300,000 CA/CAplus patent records provide insights into related prior art
NEWS 9	FEB 19	Increase the precision of your patent queries -- use terms from the IPC Thesaurus, Version 2009.01
NEWS 10	FEB 23	Several formats for image display and print options discontinued in USPATFULL and USPAT2
NEWS 11	FEB 23	MEDLINE now offers more precise author group fields and 2009 MeSH terms
NEWS 12	FEB 23	TOXCENTER updates mirror those of MEDLINE - more precise author group fields and 2009 MeSH terms
NEWS 13	FEB 23	Three million new patent records blast AEROSPACE into STN patent clusters
NEWS 14	FEB 25	USGENE enhanced with patent family and legal status display data from INPADOCDB
NEWS 15	MAR 06	INPADOCDB and INPAFAMDB enhanced with new display formats
NEWS 16	MAR 11	EPFULL backfile enhanced with additional full-text applications and grants
NEWS 17	MAR 11	ESBIOBASE reloaded and enhanced
NEWS 18	MAR 20	CAS databases on STN enhanced with new super role for nanomaterial substances
NEWS 19	MAR 23	CA/CAplus enhanced with more than 250,000 patent equivalents from China
NEWS 20	MAR 30	IMSPATENTS reloaded and enhanced
NEWS 21	APR 03	CAS coverage of exemplified prophetic substances enhanced
NEWS 22	APR 07	STN is raising the limits on saved answers
NEWS 23	APR 24	CA/CAplus now has more comprehensive patent assignee information
NEWS 24	APR 26	USPATFULL and USPAT2 enhanced with patent assignment/reassignment information
NEWS 25	APR 28	CAS patent authority coverage expanded

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 NEWS 26  APR 28  ENCOMPLIT/ENCOMPLIT2 search fields enhanced
 NEWS 27  APR 28  Limits doubled for structure searching in CAS
                  REGISTRY
 NEWS 28  MAY 08  STN Express, Version 8.4, now available
 NEWS 29  MAY 11  STN on the Web enhanced
 NEWS 30  MAY 11  BEILSTEIN substance information now available on
                  STN Easy
 NEWS 31  MAY 14  DGENE, PCTGEN and USGENE enhanced with increased
                  limits for exact sequence match searches and
                  introduction of free HIT display format
 NEWS 32  MAY 15  INPADOCDB and INPAFAMDB enhanced with Chinese legal
                  status data
 NEWS 33  MAY 28  CAS databases on STN enhanced with NANO super role in
                  records back to 1992
 NEWS 34  JUN 01  CAS REGISTRY Source of Registration (SR) searching
                  enhanced on STN

 NEWS EXPRESS MAY 26 09 CURRENT WINDOWS VERSION IS V8.4,
              AND CURRENT DISCOVER FILE IS DATED 06 APRIL 2009.

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STRUCTURE FILE UPDATES:   31 MAY 2009  HIGHEST RN 1151391-70-6
DICTIONARY FILE UPDATES:  31 MAY 2009  HIGHEST RN 1151391-70-6

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TSCA INFORMATION NOW CURRENT THROUGH January 9, 2009.
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128-37-0
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FIELD CODE - 'AND' OPERATOR ASSUMED '75980-60-8(W)OR4'
PROXIMITY OPERATOR LEVEL NOT CONSISTENT WITH
FIELD CODE - 'AND' OPERATOR ASSUMED 'OR4(W)128-37-0'
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             1 40220-08-4
                 (40220-08-4/RN)
             0 64401-02-8
             0 024650-42-8
                 (024650-42-8/RN)
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          8132 349
L3           6 SARTOMER 349
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=> s sartomer 349/cn
L4            1 SARTOMER 349/CN

=> d

L4   ANSWER 1 OF 1  REGISTRY  COPYRIGHT 2009 ACS on STN
RN   24447-78-7  REGISTRY
ED   Entered STN:  16 Nov 1984
CN   2-Propenoic acid, 1,1'-[(1-methylethylidene)bis(4,1-phenyleneoxy-2,1-
     ethanediyl)] ester  (CA INDEX NAME)
OTHER CA INDEX NAMES:
CN   2-Propenoic acid, (1-methylethylidene)bis(4,1-phenyleneoxy-2,1-ethanediyl)
     ester (9CI)
CN   Acrylic acid, diester with 2,2'-[isopropylidenebis(p-
     phenyleneoxy)]diethanol (8CI)
CN   Ethanol, 2,2'-[isopropylidenebis(p-phenyleneoxy)]di-, diacrylate (8CI)
OTHER NAMES:
CN   2,2-Bis(4-acryloxyethoxyphenyl)propane
CN   2,2-Bis[4-(2-acryloyloxyethoxy)phenyl]propane
CN   Bisphenol A bis(2-hydroxyethyl ether) diacrylate
CN   Bisphenol A bis[2-(acryloyloxy)ethyl] ether
CN   Bis[1-(2-acryloxy)-p-ethoxyphenyldimethylmethane]
CN   BR 800
CN   EB 952
CN   FM 300
CN   Kayarad FM 300
CN   Sartomer 349
CN   Sartomer SR 349
CN   Setalin AM 548
CN   Setalux UV 2246
CN   Setalux UV 2248
CN   SR 349
DR   58458-00-7, 130340-91-9, 143550-30-5, 208666-27-7
MF   C25 H28 O6
CI   COM
LC   STN Files:   CA, CAPLUS, CHEMCATS, CHEMLIST, CIN, CSCHEM, IFICDB, IFIPAT,
       IFIUDB, MSDS-OHS, PIRA, PROMT, TOXCENTER, USPAT2, USPATFULL, USPATOLD
     Other Sources:   DSL**, EINECS**, TSCA**
         (**Enter CHEMLIST File for up-to-date regulatory information)
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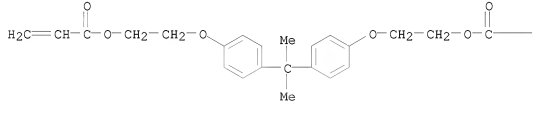
PAGE 1-A



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183 REFERENCES IN FILE CA (1907 TO DATE)
22 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA
184 REFERENCES IN FILE CAPLUS (1907 TO DATE)

=> s irgacure 651/cn
L5 1 IRGACURE 651/CN

=> d

L5 ANSWER 1 OF 1 REGISTRY COPYRIGHT 2009 ACS on STN
RN 24650-42-8 REGISTRY
ED Entered STN: 16 Nov 1984
CN Ethanone, 2,2-dimethoxy-1,2-diphenyl- (CA INDEX NAME)
OTHER CA INDEX NAMES:
CN Benzil dimethyl acetal (6CI)
OTHER NAMES:
CN α,α-Dimethoxy-α-phenylacetophenone
CN α,α-Dimethoxydeoxybenzoin
CN ω,ω-Dimethoxy-ω-phenylacetophenone
CN 1,2-Diphenyl-2,2-dimethoxyethanone
CN 2,2-Dimethoxy-1,2-diphenyl-1-ethanone
CN 2,2-Dimethoxy-1,2-diphenylethanone
CN 2,2-Dimethoxy-2-phenylacetophenone
CN 2,2-Dimethoxyphenylacetophenone
CN 2-Phenyl-2,2-dimethoxyacetophenone
CN Aronix C 101
CN BDK
CN Benzil dimethyl ketal
CN Benzil mono(dimethyl acetal)
CN Benzil mono(dimethyl ketal)
CN Benzoin dimethyl ether
CN C 101
CN DMPA
CN Esacure KB 1
CN I 651
CN IR 651
CN IRG 651
CN Irgacure 621
CN Irgacure 641
CN Irgacure 651
CN Irgacure 654
CN Irgacure 671
CN Irgacure 951
CN Irgacure E 651
CN Irgacure I 651

CN Kayacure BDMK
CN KB 1
CN Lucirin BDK
CN Micure BK 6
CN Photomer 51
CN Quantacure BDK
DR 123584-60-1, 68072-91-3, 85568-54-3, 89697-37-0, 91234-65-0, 91274-91-8, 88658-61-1, 190337-02-1
MF C16 H16 O3
CI COM
LC STN Files: ADISNEWS, AGRICOLA, ANABSTR, BEILSTEIN*, BIOSIS, CA, CAPLUS, CASREACT, CHEMCATS, CHEMINFORMRX, CHEMLIST, CIN, CSCHEM, DETHERM*, IFICDB, IFIPAT, IFIUDB, IPA, MEDLINE, MSDS-OHS, PIRA, PROMT, RTECS*, SPECINFO, TOXCENTER, USPAT2, USPATFULL
(*File contains numerically searchable property data)
Other Sources: DSL**, EINECS**, TSCA**
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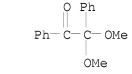

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3530 REFERENCES IN FILE CA (1907 TO DATE)
17 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA
3548 REFERENCES IN FILE CAPLUS (1907 TO DATE)

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(FILE 'HOME' ENTERED AT 14:17:34 ON 01 JUN 2009)

FILE 'REGISTRY' ENTERED AT 14:17:54 ON 01 JUN 2009
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L2 4 S 42594-17-2 OR 40220-08-4 OR 64401-02-8 OR 024650-42-8 OR 7598
L3 6 S SARTOMER 349
L4 1 S SARTOMER 349/CN
L5 1 S IRGACURE 651/CN

=> d l2 1-4

L2 ANSWER 1 OF 4 REGISTRY COPYRIGHT 2009 ACS on STN
RN 75980-60-8 REGISTRY
ED Entered STN: 16 Nov 1984
CN Methanone, (diphenylphosphinyl)(2,4,6-trimethylphenyl)- (CA INDEX NAME)
OTHER CA INDEX NAMES:
CN Phosphine oxide, diphenyl(2,4,6-trimethylbenzoyl)- (9CI)
OTHER NAMES:
CN (2,4,6-Trimethylbenzoyl)diphenylphosphine oxide
CN Chivacure TPO
CN Darocur TPO

CN Darocure TPO
CN Diphenyl(2,4,6-trimethylbenzoyl)phosphine oxide
CN Genocure TPO
CN Irgacure TPO
CN L-TPO
CN Lucirin 8893X
CN Lucirin LR 8728
CN Lucirin LR 8893
CN Lucirin LR 8953
CN Lucirin TPO
CN Lucirin TPO Solid
CN Lucirin TPO-X
CN Photocure TPO
CN Speedcure TPO
CN TPO
CN TPO-X
DR 596818-40-5
MF C22 H21 O2 P
CI COM
LC STN Files: BEILSTEIN*, CA, CAPLUS, CASREACT, CHEMCATS, CHEMLIST, CIN, CSCHEM, MSDS-OHS, RTECS*, SPECINFO, TOXCENTER, USPAT2, USPATFULL
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Other Sources: DSL**, EINECS**, TSCA**
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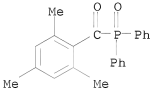

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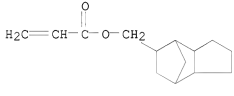
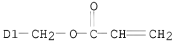
1345 REFERENCES IN FILE CAPLUS (1907 TO DATE)

L2 ANSWER 2 OF 4 REGISTRY COPYRIGHT 2009 ACS on STN
RN 42594-17-2 REGISTRY
ED Entered STN: 16 Nov 1984
CN 2-Propenoic acid, 1,1'-[(octahydro-4,7-methano-1H-indene-5,?-diyl)bis(methylene)] ester (CA INDEX NAME)
OTHER CA INDEX NAMES:
CN 2-Propenoic acid, (octahydro-4,7-methano-1H-indene-5,?-diyl)bis(methylene) ester (9CI)
OTHER NAMES:
CN 2-Propenoic acid, [octahydro-4,7-methano-1H-indene-1,5(1,6 or 2,5)diyl]bis(methylene) ester
CN A-DCP
CN Aronix M 203
CN Bis(acryloyloxymethyl)tricyclo[5.2.1.02,6]decane
CN Bis(hydroxymethyl)tricyclo[5.2.1.02,6]decane diacrylate
CN DCP-A

CN Dicyclopentadienedimethanol diacrylate
CN Dicyclopentyldimethylene diacrylate
CN Dimethyloltricyclodecane diacrylate
CN Ebecryl 130
CN IRR 214
CN IRR 214K
CN Kayarad DCP-A
CN Kayarad R 684
CN Light Acrylate DCP-A
CN M 203
CN M 260
CN NK Ester A-DCP
CN R 684
CN SA 1002
CN Sinfony Activator
CN Sinfony dentin
CN SR 833
CN SR 833S
CN Tricyclodecanedimethanol diacrylate
CN Yupimer SA 1002
CN Yupimer UV-SA 1002
DR 951693-72-4, 658700-25-5, 125175-93-1, 147392-96-9, 147392-97-0, 79882-73-8, 181726-00-1, 205050-35-7, 491876-38-1
MF C18 H24 O4
CI IDS, COM
LC STN Files: CA, CAPLUS, CHEMCATS, CHEMLIST, CIN, IFICDB, IFIPAT, IFIUDB, TOXCENTER, USPAT2, USPATFULL
Other Sources: DSL**, EINECS**, TSCA**
(**Enter CHEMLIST File for up-to-date regulatory information)





PROPERTY DATA AVAILABLE IN THE 'PROP' FORMAT

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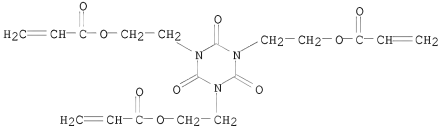
146 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA
395 REFERENCES IN FILE CAPLUS (1907 TO DATE)

L2 ANSWER 3 OF 4 REGISTRY COPYRIGHT 2009 ACS on STN
RN 40220-08-4 REGISTRY
ED Entered STN: 16 Nov 1984
CN 2-Propenoic acid, 1,1',1''-[(2,4,6-trioxo-1,3,5-triazine-1,3,5(2H,4H,6H)-triyl)tri-2,1-ethanediyl] ester (CA INDEX NAME)

OTHER CA INDEX NAMES:
CN 2-Propenoic acid, (2,4,6-trioxo-1,3,5-triazine-1,3,5(2H,4H,6H)-triyl)tri-2,1-ethanediyl ester (9CI)
OTHER NAMES:
CN A 9300
CN Aronix M 315
CN CN 936
CN Ebecryl IRR 264
CN FA 731A
CN Fancryl FA 731A
CN Genomer T 930
CN GX 8430
CN M 315
CN Newfrontier GX 8430
CN Newfrontier TEICA
CN NK Ester A 9300
CN Sartomer 368
CN Sartomer 369
CN Sartomer SR 368
CN SR 360
CN SR 368
CN THEICTA
CN Tris(β-acryloyloxyethyl) isocyanurate
CN Tris(2-acryloxyethyl) isocyanurate
CN Tris(2-hydroxyethyl) isocyanurate triacrylate
CN Tris(2-hydroxyethyl)isocyanuric acid triacrylate
CN Tris(acryloyloxyethyl) isocyanurate
CN Tris[2-(acryloyloxy)ethyl] isocyanurate
DR 98940-65-9, 115753-22-5, 112385-00-9, 76364-14-2, 116107-64-3, 182077-88-9
MF C18 H21 N3 O9
CI COM
LC STN Files: BIOSIS, CA, CAPLUS, CHEMCATS, CHEMLIST, CIN, CSCHEM, IFICDB, IFIPAT, IFIUDB, TOXCENTER, USPAT2, USPATFULL, USPATOLD
Other Sources: EINECS**, NDSL**, TSCA**
(**Enter CHEMLIST File for up-to-date regulatory information)



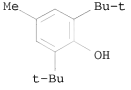
PROPERTY DATA AVAILABLE IN THE 'PROP' FORMAT

688 REFERENCES IN FILE CA (1907 TO DATE)
152 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA
689 REFERENCES IN FILE CAPLUS (1907 TO DATE)

L2 ANSWER 4 OF 4 REGISTRY COPYRIGHT 2009 ACS on STN
RN 128-37-0 REGISTRY

ED Entered STN: 16 Nov 1984
CN Phenol, 2,6-bis(1,1-dimethylethyl)-4-methyl- (CA INDEX NAME)
OTHER NAMES:
CN 2,6-Bis(1,1-dimethylethyl)-4-methylphenol
CN 2,6-Bis(tert-butyl)-4-methylphenol
CN 2,6-Di(tert-butyl)hydroxytoluene
CN 2,6-Di-tert-butyl-4-cresol
CN 2,6-Di-tert-butyl-4-hydroxytoluene
CN 2,6-Di-tert-butyl-4-methyl-1-hydroxybenzene
CN 2,6-Di-tert-butyl-4-methylhydroxybenzene
CN 2,6-Di-tert-butyl-4-methylphenol
CN 2,6-Di-tert-butyl-p-cresol
CN 2,6-Di-tert-butyl-p-cresol
CN 2,6-Di-tert-butyl-p-cresole
CN 2,6-Di-tert-butyl-p-methylphenol
CN 2,6-Di-tert-butylcresol
CN 2,6-Di-tert-butylmethylphenol
CN 2,6-tert-Butyl-4-methylphenol
CN 3,5-Di-tert-butyl-4-hydroxytoluene
CN 3,5-Di-tert-butyl-p-hydroxytoluene
CN 4-Hydroxy-3,5-di-tert-butyltoluene
CN 4-Methyl-2,6-bis(1,1-dimethylethyl)phenol
CN 4-Methyl-2,6-di-tert-butylphenol
CN Advastab 401
CN Agidol
CN Agidol 1
CN Agidol 1A
CN Alkofen BP
CN Antage BHT
CN Antioxidant 246
CN Antioxidant 264
CN Antioxidant 29
CN Antioxidant 30
CN Antioxidant 4
CN Antioxidant 4K
CN Antioxidant DBPC
CN Antioxidant KB
CN Antioxidant MPJ
CN Antioxidant T 501
CN Antox QT
CN AO 29
CN AO 4
CN AO 4K
CN AOX 4
CN AOX 4K
CN B-NOX BHT-P
CN BAT
CN BHT
CN BHT 264
CN BHT Swanox
CN BHT-C
CN Buks
CN Butylated hydroxytoluene
ADDITIONAL NAMES NOT AVAILABLE IN THIS FORMAT - Use FCN, FIDE, or ALL for DISPLAY
DR 53571-70-3, 58500-82-6, 97123-41-6, 102962-45-8, 50641-99-1, 36631-28-4, 83047-16-9, 42615-30-5, 50356-19-9, 52683-46-2, 259752-53-9, 290348-23-1

MF C15 H24 O
CI COM
LC STN Files: ADISNEWS, AGRICOLA, ANABSTR, AQUIRE, BEILSTEIN*, BIOSIS, BIOTECHNO, CA, CABA, CAPLUS, CASREACT, CBNB, CHEMCATS, CHEMINFORMRX, CHEMLIST, CIN, CSCHEM, CSNB, DDFU, DETHERM*, DRUGU, EMBASE, ENCOMPLIT, ENCOMPLIT2, ENCOMPPAT, ENCOMPPAT2, GMELIN*, HSDB*, IFICDB, IFIPAT, IFIUDB, IPA, MEDLINE, MRCK*, MSDS-OHS, NAPRALERT, PHAR, PIRA, PROMT, RTECS*, SPECINFO, SYNTHLINE, TOXCENTER, ULIDAT, USAN, USPAT2, USPATFULL
      (*File contains numerically searchable property data)
    Other Sources: DSL**, EINECS**, TSCA**
      (**Enter CHEMLIST File for up-to-date regulatory information)



PROPERTY DATA AVAILABLE IN THE 'PROP' FORMAT

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          143 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA
        17259 REFERENCES IN FILE CAPLUS (1907 TO DATE)

=> s 42594-17-2/crn and 40220-08-4/crn and 24447-78-7/crn
        1064 42594-17-2/CRN
        1033 40220-08-4/CRN
         279 24447-78-7/CRN
L6   1 42594-17-2/CRN AND 40220-08-4/CRN AND 24447-78-7/CRN

=> d

L6 ANSWER 1 OF 1 REGISTRY COPYRIGHT 2009 ACS on STN
RN 866129-61-5 REGISTRY
ED Entered STN: 26 Oct 2005
CN 2-Propenoic acid, (2,4,6-trioxo-1,3,5-triazine-1,3,5(2H,4H,6H)-triyl)tri-2,1-ethanediyl ester, polymer with Ebecryl 8402, α-hydro-ω-(3-mercapto-1-oxopropoxy)poly(oxy-1,2-ethanediyl) ether with 2-ethyl-2-(hydroxymethyl)-1,3-propanediol (3:1), (1-methylethylidene)bis(4,1-phenyleneoxy-2,1-ethanediyl) di-2-propenoate and (octahydro-4,7-methano-1H-indene-5,?-diyl)bis(methylene) di-2-propenoate (9CI) (CA INDEX NAME)
OTHER NAMES:
CN Ebecryl 8402-ethoxylated trimethylolpropane tris-3-mercaptopropionate-Sartomer 349-Sartomer 368-SR 833s copolymer
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CI PMS
PCT Manual component, Polyacrylic, Polyether, Polyother
SR CA
LC STN Files: CA, CAPLUS, USPATFULL

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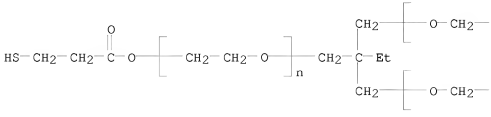

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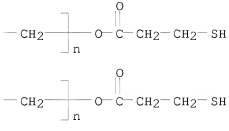

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CCI PMS, MAN

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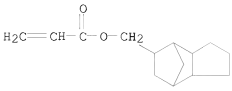

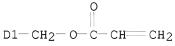

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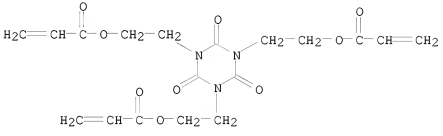

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CMF C25 H28 O6

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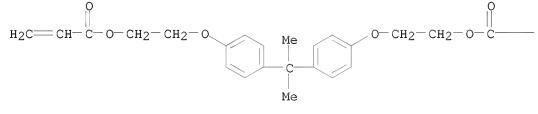

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1 REFERENCES IN FILE CA (1907 TO DATE)
1 REFERENCES IN FILE CAPLUS (1907 TO DATE)

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L7 1 EBECRYL 8402/CN

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L7 ANSWER 1 OF 1 REGISTRY COPYRIGHT 2009 ACS on STN
RN 183449-62-9 REGISTRY
ED Entered STN: 27 Nov 1996
CN Ebecryl 8402 (CA INDEX NAME)
OTHER NAMES:
CN EB 8402
CN EBC 8402
CN Ebecryl EB 8402
ENTE An aliphatic urethane acrylate (Cray Valley)
MF Unspecified
CI PMS, COM, MAN
PCT Manual registration
SR CA
LC STN Files: CA, CAPLUS, TOXCENTER, USPAT2, USPATFULL

*** STRUCTURE DIAGRAM IS NOT AVAILABLE ***
32 REFERENCES IN FILE CA (1907 TO DATE)
8 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA
32 REFERENCES IN FILE CAPLUS (1907 TO DATE)

=> file caplus

COST IN U.S. DOLLARS	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	64.96	65.18

FILE 'CAPLUS' ENTERED AT 14:25:03 ON 01 JUN 2009
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FILE COVERS 1907 - 1 Jun 2009 VOL 150 ISS 23
FILE LAST UPDATED: 31 May 2009 (20090531/ED)
REVISED CLASS FIELDS (/NCL) LAST RELOADED: Feb 2009
USPTO MANUAL OF CLASSIFICATIONS THESAURUS ISSUE DATE: Feb 2009

CAplus now includes complete International Patent Classification (IPC)
reclassification data for the third quarter of 2008.

CAS Information Use Policies apply and are available at:

http://www.cas.org/legal/infopolicy.html

This file contains CAS Registry Numbers for easy and accurate

=>

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L3 6 S SARTOMER 349
L4 1 S SARTOMER 349/CN
L5 1 S IRGACURE 651/CN
L6 1 S 42594-17-2/CRN AND 40220-08-4/CRN AND 24447-78-7/CRN
L7 1 S EBECRYL 8402/CN

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L8 ANSWER 1 OF 1 CAPLUS COPYRIGHT 2009 ACS on STN
AN 2005:1075719 CAPLUS
DN 143:368247
ED Entered STN: 07 Oct 2005
TI Photocurable compositions suitable for optical molding
IN Patel, Ranjana C.; Rhodes, Michael; Zhao, Yong
PA Huntsman Advanced Materials Switzerland G.m.b.H., Switz.
SO PCT Int. Appl., 42 pp.
CODEN: PIXXD2
DT Patent
LA English
IC ICM B29C067-00
ICS G03F007-027; B29K033-00
CC 38-2 (Plastics Fabrication and Uses)
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 2005092598	A1	20051006	WO 2005-EP51287	20050321

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            GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC,
            LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI,
            NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM,
            SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW
        RW: BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM,
            AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK,
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            RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML,
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    EP 1727663          A1    20061206    EP 2005-729543         20050321
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    KR 2007005638       A     20070110    KR 2006-719508         20060921
    US 20070205528      A1    20070906    US 2006-593746         20060922
PRAI EP 2004-251653     A     20040322
    WO 2005-EP51287     W     20050321
CLASS
 PATENT NO.      CLASS  PATENT FAMILY CLASSIFICATION CODES
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                 IPCI   B29C0067-00 [ICM,7]; G03F0007-027 [ICS,7]; B29K0033-00
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IN 2006DN04957 IPCI B29C0067-00 [ICM,7]
KR 2007005638 IPCI G03F0007-027 [I,A]; B29C0067-00 [I,A]
ECLA G03F007/00S; G03F007/038; L29C; L29C
US 20070205528 IPCI A61C0013-00 [I,A]
NCL 264/016.000

AB An optical molding process comprises the sequential steps of (a)(y) forming a layer of a photocurable composition and (bXz) irradiating selected areas of the composition in the layer with radiation, curing the composition in the selected areas and repeating the steps (a) and (b) on top of an earlier cured layer to form a 3-dimensional structure, where the radiation source used in step (b) is a noncoherent source of radiation and where the photocurable composition comprises ≥2 curable components: (i) 45-95% (and preferably ≥50%, more preferably ≥70%) component that is photocurable and that is such that, when cured in the presence of a photocuring initiator by exposure to UV radiation (30 mJ/cm2), ≥90% of the component is cured within 50 ms, and (ii) 5-55% (and preferably 10-40%, more preferably 15-30%, e.g. .apprx.20%) component that results in the composition, on curing, shrinking in a linear direction by <3% and preferably that results in the composition having, after cure, a Tg >50°, preferably ≥100° and more preferably ≥120°.

ST rapid prototyping acrylic polythiol photopolymer blend UV cure

IT Stereolithography
(UV-based; of photocurable compns. for optical moldings)

IT Molding of plastics and rubbers
(optical, layerwise; of photocurable compns. for optical moldings)

IT Acrylic polymers, uses
RL: IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(photocurable compns. for optical moldings)

IT Thiols, uses
RL: IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(polythiols; photocurable compns. for optical moldings)

IT 866129-61-5P, Ebecryl 8402-ethoxylated Trimethylolpropane tris-3-mercaptopropionate-Sartomer 349-Sartomer 368-SR 833s copolymer 866129-63-7P, Sartomer 349-UVACURE 1500-UVR 6000 copolymer
RL: IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(photocurable compns. for optical moldings)

RE.CNT 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

(1) Ciba Geigy Ag; DE 4440819 A 1995 CAPLUS
(2) Dicon, A; WO 0021735 A 2000
(3) Dsm Ip Assets B V; EP 1477511 A 2004 CAPLUS
(4) Ivoclar Vivadent Ag; EP 1243231 A 2002 CAPLUS
(5) Loctite Corp; EP 0492953 A 1992 CAPLUS
(6) Miller, L; US 5250391 A 1993 CAPLUS
(7) Miller, L; US 5397662 A 1995
(8) Mitsubishi Chemical Corporation; EP 1275668 A 2003 CAPLUS

(9) Moyer, J; US 4230740 A 1980 CAPLUS
(10) Paul, K; WO 0055272 A 2000 CAPLUS

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L15   2 L14 AND L12 AND L10

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L15 ANSWER 1 OF 2 CAPLUS COPYRIGHT 2009 ACS on STN
AN   2005:1075719 CAPLUS
DN   143:368247
ED   Entered STN: 07 Oct 2005
TI   Photocurable compositions suitable for optical molding
IN   Patel, Ranjana C.; Rhodes, Michael; Zhao, Yong
PA   Huntsman Advanced Materials Switzerland G.m.b.H., Switz.
SO   PCT Int. Appl., 42 pp.
     CODEN: PIXXD2

DT Patent
LA English
IC ICM B29C067-00
ICS G03F007-027; B29K033-00
CC 38-2 (Plastics Fabrication and Uses)
FAN.CNT 1

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	KR 2007005638	A	20070110	KR 2006-719508	20060921
	US 20070205528	A1	20070906	US 2006-593746	20060922
PRAI	EP 2004-251653	A	20040322		
	WO 2005-EP51287	W	20050321		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
WO 2005092598	ICM	B29C067-00
	ICS	G03F007-027; B29K033-00
	IPCI	B29C0067-00 [ICM,7]; G03F0007-027 [ICS,7]; B29K0033-00 [ICS,7]
	IPCR	B29C0035-08 [N,C*]; B29C0035-08 [N,A]; B29C0067-00 [I,C*]; B29C0067-00 [I,A]; G03F0007-00 [I,C*]; G03F0007-00 [I,A]; G03F0007-027 [I,C*]; G03F0007-027 [I,A]; G03F0007-038 [I,C*]; G03F0007-038 [I,A]
	ECLA	G03F007/00S; G03F007/038; L29C; L29C
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	ECLA	G03F007/00S; G03F007/038; L29C; L29C
JP 2007530724	IPCI	C08G0085-00 [I,A]; B29C0067-00 [I,A]
	IPCR	C08G0085-00 [I,C]; C08G0085-00 [I,A]; B29C0035-08 [N,C*]; B29C0035-08 [N,A]; B29C0067-00 [I,C]; B29C0067-00 [I,A]; G03F0007-00 [I,C*]; G03F0007-00 [I,A]; G03F0007-027 [I,C*]; G03F0007-027 [I,A]; G03F0007-038 [I,C*]; G03F0007-038 [I,A]
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KR 2007005638	IPCI	G03F0007-027 [I,A]; B29C0067-00 [I,A]
	ECLA	G03F007/00S; G03F007/038; L29C; L29C
US 20070205528	IPCI	A61C0013-00 [I,A]
	NCL	264/016.000

AB An optical molding process comprises the sequential steps of (a)(y) forming a layer of a photocurable composition and (bXz) irradiating selected areas of the composition in the layer with radiation, curing the composition in the selected areas and repeating the steps (a) and (b) on top of an earlier cured layer to form a 3-dimensional structure, where the radiation source used in step (b) is a noncoherent source of radiation and where the photocurable composition comprises ≥2 curable components: (i) 45-95% (and preferably ≥50%, more preferably ≥70%) component that is photocurable and that is such that, when cured in the presence of a photocuring initiator by exposure to UV radiation (30 mJ/cm2), ≥90% of the component is cured within 50 ms, and (ii) 5-55% (and preferably 10-40%, more preferably 15-30%, e.g. .apprx.20%) component that results in the composition, on curing, shrinking in a linear direction by <3% and preferably that results in the composition having, after cure, a Tg >50°, preferably ≥100° and more preferably ≥120°.

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RL: IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(polythiols; photocurable compns. for optical moldings)

IT 866129-61-5P, Ebecryl 8402-ethoxylated Trimethylolpropane tris-3-mercaptopropionate-Sartomer 349-Sartomer 368-SR 833s copolymer 866129-63-7P, Sartomer 349-UVACURE 1500-UVR 6000 copolymer
RL: IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(photocurable compns. for optical moldings)

RE.CNT 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE
(1) Ciba Geigy Ag; DE 4440819 A 1995 CAPLUS
(2) Dicon, A; WO 0021735 A 2000
(3) Dsm Ip Assets B V; EP 1477511 A 2004 CAPLUS
(4) Ivoclar Vivadent Ag; EP 1243231 A 2002 CAPLUS
(5) Loctite Corp; EP 0492953 A 1992 CAPLUS
(6) Miller, L; US 5250391 A 1993 CAPLUS
(7) Miller, L; US 5397662 A 1995
(8) Mitsubishi Chemical Corporation; EP 1275668 A 2003 CAPLUS
(9) Moyer, J; US 4230740 A 1980 CAPLUS
(10) Paul, K; WO 0055272 A 2000 CAPLUS

L15 ANSWER 2 OF 2 CAPLUS COPYRIGHT 2009 ACS on STN
AN 1998:684925 CAPLUS
DN 129:303473
OREF 129:61899a,61902a
ED Entered STN: 29 Oct 1998
TI Circuit connecting materials, and structure and method of connecting circuit terminal
IN Watanabe, Itsuo; Fujinawa, Touru; Arifuku, Motohiro; Kanazawa, Houko; Kuwano, Atsusi
PA Hitachi Chemical Co., Ltd., Japan
SO PCT Int. Appl., 56 pp.
CODEN: PIXXD2
DT Patent
LA Japanese
IC ICM C09J201-00
ICS C09J009-02; C09J161-00; C09J163-00; C08L101-00; C08L061-00; C08L063-00; C08K005-14; H01B001-20; H01L021-60
CC 38-3 (Plastics Fabrication and Uses)
Section cross-reference(s): 76
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI WO 9844067	A1	19981008	WO 1998-JP1467	19980331
W: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, GM, GW, HU, ID, IL, IS, JP, KE, KG, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ZW				
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AU 9865207	A	19981022	AU 1998-65207	19980331
EP 979854	A1	20000216	EP 1998-911125	19980331
EP 979854	B1	20061004		
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JP 3587859	B2	20041110	JP 1998-541457	19980331
TW 229119	B	20050311	TW 1998-87104823	19980331
EP 1542273	A1	20050615	EP 2004-28659	19980331
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EP 1717851	A1	20061102	EP 2006-115661	19980331
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EP 1890324	A2	20080220	EP 2007-114390	19980331
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JP	2004128465	A	20040422	JP 2003-186397	20030630
US	20040222408	A1	20041111	US 2004-860578	20040604
JP	2005298828	A	20051027	JP 2005-116155	20050413
JP	4265565	B2	20090520		
JP	2005307210	A	20051104	JP 2005-116151	20050413
JP	2005314696	A	20051110	JP 2005-116147	20050413
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US	20060014860	A1	20060119	US 2005-227186	20050916
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PRAI JP	1997-79422	A	19970331		
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JP	2003-186397	A3	20030630		
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US	2005-227186	A3	20050916		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
WO 9844067	ICM	C09J201-00
	ICS	C09J009-02; C09J161-00; C09J163-00; C08L101-00; C08L061-00; C08L063-00; C08K005-14; H01B001-20; H01L021-60
	IPCI	C09J0201-00 [ICM,6]; C09J0009-02 [ICS,6]; C09J0009-00 [ICS,6,C*]; C09J0161-00 [ICS,6]; C09J0163-00 [ICS,6]; C08L0101-00 [ICS,6]; C08L0061-00 [ICS,6]; C08L0063-00 [ICS,6]; C08K0005-14 [ICS,6]; C08K0005-00 [ICS,6,C*]; H01B0001-20 [ICS,6]; H01L0021-60 [ICS,6]; H01L0021-02 [ICS,6,C*]
	IPCR	C08K0005-00 [N,C*]; C08K0005-14 [N,A]; C08K0005-521 [N,A]; C08L0009-00 [N,C*]; C08L0009-02 [N,A]; C08L0013-00 [N,C*]; C08L0013-00 [N,A]; C08L0021-00 [N,C*]; C08L0021-00 [N,A]; C09J0201-00 [I,C*]; C09J0201-06 [I,A]; H01B0001-20 [I,C*]; H01B0001-20 [I,A]; H01L0021-02 [I,C*]; H01L0021-60 [I,A]; H01L0023-28 [I,C*]; H01L0023-29 [I,A]; H05K0003-32 [I,C*]; H05K0003-32 [I,A]
	ECLA	C09J201/06; H01B001/20; H01L021/60C4; H01L021/60D; H01L023/29P; H05K003/32B2; M08K; M08K; M08L; M08L; M08L
AU 9865207	IPCI	C09J0201-00 [ICM,6]; C09J0009-02 [ICS,6]; C09J0009-00 [ICS,6,C*]; C09J0161-00 [ICS,6]; C09J0163-00 [ICS,6]; C08L0101-00 [ICS,6]; C08L0061-00 [ICS,6]; C08L0063-00 [ICS,6]; C08K0005-14 [ICS,6]; C08K0005-00 [ICS,6,C*]; H01B0001-20 [ICS,6]; H01L0021-60 [ICS,6]; H01L0021-02 [ICS,6,C*]
	IPCR	C08K0005-00 [N,C*]; C08K0005-14 [N,A]; C08K0005-521 [N,A]; C08L0009-00 [N,C*]; C08L0009-02 [N,A];

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	ECLA	C09J201/06; H01B001/20; H01L021/60C4; H01L021/60D; H01L023/29P; H05K003/32B2; M08K; M08K; M08L; M08L; M08L
EP 979854	IPCI	C09J0201-00 [I,C]; C08K0005-00 [I,C]; C08L0061-00 [I,C]; C08L0063-00 [I,C]; C08L0101-00 [I,C]; C09J0009-00 [I,C]; C09J0161-00 [I,C]; C09J0163-00 [I,C]; C09J0163-02 [I,C]; C09J0171-00 [I,C]; H01B0001-20 [I,C]; H01L0021-02 [I,C]; H05K0003-32 [I,C]; C09J0201-00 [I,A]; C08K0005-14 [I,A]; C08L0061-00 [I,A]; C08L0063-00 [I,A]; C08L0101-00 [I,A]; C09J0009-02 [I,A]; C09J0161-00 [I,A]; C09J0163-00 [I,A]; C09J0163-02 [I,A]; C09J0171-00 [I,A]; H01B0001-20 [I,A]; H01L0021-60 [I,A]; H05K0003-32 [I,A]
	IPCR	C09J0201-00 [I,C]; C09J0201-00 [I,A]; C08K0005-00 [I,C]; C08K0005-14 [I,A]; C08K0005-521 [N,A]; C08L0009-00 [N,C*]; C08L0009-02 [N,A]; C08L0013-00 [N,C*]; C08L0013-00 [N,A]; C08L0021-00 [N,C*]; C08L0021-00 [N,A]; C08L0061-00 [I,C]; C08L0061-00 [I,A]; C08L0063-00 [I,C]; C08L0063-00 [I,A]; C08L0101-00 [I,C]; C08L0101-00 [I,A]; C09J0009-00 [I,C]; C09J0009-02 [I,A]; C09J0161-00 [I,C]; C09J0161-00 [I,A]; C09J0163-00 [I,C]; C09J0163-00 [I,A]; C09J0163-02 [I,C]; C09J0163-02 [I,A]; C09J0171-00 [I,C]; C09J0171-00 [I,A]; C09J0201-06 [I,A]; H01B0001-20 [I,C]; H01B0001-20 [I,A]; H01L0021-02 [I,C]; H01L0021-60 [I,A]; H01L0023-28 [I,C*]; H01L0023-29 [I,A]; H05K0003-32 [I,C]; H05K0003-32 [I,A]
	ECLA	C09J201/06; H01B001/20; H01L021/60C4; H01L021/60D; H01L023/29P; H05K003/32B2; M08K; M08K; M08L; M08L; M08L
JP 3587859	IPCI	C09J0201-00 [ICM,7]; C08K0005-14 [ICS,7]; C08K0005-00 [ICS,7,C*]; C08L0061-00 [ICS,7]; C08L0063-00 [ICS,7]; C08L0101-00 [ICS,7]; C09J0009-02 [ICS,7]; C09J0009-00 [ICS,7,C*]; C09J0161-00 [ICS,7]; C09J0163-00 [ICS,7]; H01B0001-20 [ICS,7]; H01L0021-60 [ICS,7]; H01L0021-02 [ICS,7,C*]
	IPCR	C08K0005-00 [N,C*]; C08K0005-14 [N,A]; C08K0005-521 [N,A]; C08L0009-00 [N,C*]; C08L0009-02 [N,A]; C08L0013-00 [N,C*]; C08L0013-00 [N,A]; C08L0021-00 [N,C*]; C08L0021-00 [N,A]; C09J0201-00 [I,C*]; C09J0201-06 [I,A]; H01B0001-20 [I,C*]; H01B0001-20 [I,A]; H01L0021-02 [I,C*]; H01L0021-60 [I,A]; H01L0023-28 [I,C*]; H01L0023-29 [I,A]; H05K0003-32 [I,C*]; H05K0003-32 [I,A]
	ECLA	C09J201/06; H01B001/20; H01L021/60C4; H01L021/60D; H01L023/29P; H05K003/32B2; M08K; M08K; M08L; M08L; M08L
TW 229119	IPCI	C09J0007-00 [ICS,7]; H01L0021-00 [ICS,7]
	IPCR	C08K0005-00 [N,C*]; C08K0005-14 [N,A]; C08K0005-521 [N,A]; C08L0009-00 [N,C*]; C08L0009-02 [N,A]; C08L0013-00 [N,C*]; C08L0013-00 [N,A]; C08L0021-00 [N,C*]; C08L0021-00 [N,A]; C09J0201-00 [I,C*];

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	ECLA	C09J201/06; H01B001/20; H01L021/60C4; H01L021/60D; H01L023/29P; H05K003/32B2; M08K; M08K; M08L; M08L; M08L
EP 1542273	IPCI	H01L0021-60 [ICM,7]; H01L0021-02 [ICM,7,C*]; C09J0157-00 [ICS,7]
	IPCR	C08K0005-00 [N,C*]; C08K0005-14 [N,A]; C08K0005-521 [N,A]; C08L0009-00 [N,C*]; C08L0009-02 [N,A]; C08L0013-00 [N,C*]; C08L0013-00 [N,A]; C08L0021-00 [N,C*]; C08L0021-00 [N,A]; C09J0157-00 [I,C*]; C09J0157-00 [I,A]; C09J0201-00 [I,C*]; C09J0201-06 [I,A]; H01B0001-20 [I,C*]; H01B0001-20 [I,A]; H01B0001-22 [I,C*]; H01B0001-22 [I,A]; H01L0021-02 [I,C*]; H01L0021-60 [I,A]; H01L0023-28 [I,C*]; H01L0023-29 [I,A]; H05K0003-32 [I,C*]; H05K0003-32 [I,A]
	ECLA	C09J201/06; H01B001/20; H01B001/22; H01L021/60C4; H01L021/60D; H01L023/29P; H05K003/32B2; M08K; M08K; M08L; M08L; M08L
EP 1717851	IPCI	H01L0021-60 [I,A]; H01L0021-02 [I,C*]; H01L0023-29 [I,A]; H01L0023-28 [I,C*]; H05K0003-32 [I,A]; C09J0201-00 [I,A]; C09J0009-02 [I,A]; C09J0009-00 [I,C*]; C09J0161-00 [I,A]; C09J0163-00 [I,A]; C08L0061-00 [I,A]; C08L0063-00 [I,A]; C08K0005-14 [I,A]; C08K0005-00 [I,C*]
	IPCR	H01L0021-02 [I,C]; H01L0021-60 [I,A]; C08K0005-00 [I,C]; C08K0005-14 [I,A]; C08K0005-521 [N,A]; C08L0009-00 [N,C*]; C08L0009-02 [N,A]; C08L0013-00 [N,C*]; C08L0013-00 [N,A]; C08L0021-00 [N,C*]; C08L0021-00 [N,A]; C08L0061-00 [I,C]; C08L0061-00 [I,A]; C08L0063-00 [I,C]; C08L0063-00 [I,A]; C09J0009-00 [I,C]; C09J0009-02 [I,A]; C09J0157-00 [I,C*]; C09J0157-00 [I,A]; C09J0161-00 [I,C]; C09J0161-00 [I,A]; C09J0163-00 [I,C]; C09J0163-00 [I,A]; C09J0201-00 [I,C]; C09J0201-00 [I,A]; C09J0201-06 [I,A]; H01B0001-20 [I,C*]; H01B0001-20 [I,A]; H01B0001-22 [I,C*]; H01B0001-22 [I,A]; H01L0023-28 [I,C]; H01L0023-29 [I,A]; H05K0003-32 [I,C]; H05K0003-32 [I,A]
	ECLA	C09J201/06; H01B001/20; H01B001/22; H01L021/60C4; H01L021/60D; H01L023/29P; H05K003/32B2; M08K; M08K; M08L; M08L; M08L
EP 1890324	IPCI	H01L0021-60 [I,A]; H01L0021-02 [I,C*]; H01L0023-29 [I,A]; H01L0023-28 [I,C*]; H05K0003-32 [I,A]; C09J0201-00 [I,A]; C09J0009-02 [I,A]; C09J0009-00 [I,C*]; C09J0161-00 [I,A]; C09J0163-00 [I,A]; C08L0061-00 [I,A]; C08L0063-00 [I,A]; C08K0005-14 [I,A]; C08K0005-00 [I,C*]
	IPCR	H01L0021-02 [I,C]; H01L0021-60 [I,A]; C08K0005-00 [I,C]; C08K0005-14 [I,A]; C08K0005-521 [N,A]; C08L0009-00 [N,C*]; C08L0009-02 [N,A]; C08L0013-00 [N,C*]; C08L0013-00 [N,A]; C08L0021-00 [N,C*]; C08L0021-00 [N,A]; C08L0061-00 [I,C]; C08L0061-00 [I,A]; C08L0063-00 [I,C]; C08L0063-00 [I,A]; C09J0009-00 [I,C]; C09J0009-02 [I,A]; C09J0161-00

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	ECLA	C09J201/06; H01B001/20; H01L021/60C4; H01L021/60D; H01L023/29P; H05K003/32B2; M08K; M08K; M08L; M08L; M08L
US 6777464	IPCI	C08K0003-08 [ICM,7]; C08K0003-00 [ICM,7,C*]; C08L0063-02 [ICS,7]; C08L0063-00 [ICS,7,C*]
	IPCR	C08K0005-00 [N,C*]; C08K0005-14 [N,A]; C08K0005-521 [N,A]; C08L0009-00 [N,C*]; C08L0009-02 [N,A]; C08L0013-00 [N,C*]; C08L0013-00 [N,A]; C08L0021-00 [N,C*]; C08L0021-00 [N,A]; C09J0201-00 [I,C*]; C09J0201-06 [I,A]; H01B0001-20 [I,C*]; H01B0001-20 [I,A]; H01L0021-02 [I,C*]; H01L0021-60 [I,A]; H01L0023-28 [I,C*]; H01L0023-29 [I,A]; H05K0003-32 [I,C*]; H05K0003-32 [I,A]
	NCL	523/457.000; 257/E21.511; 257/E21.514; 257/E23.119; 523/458.000; 523/459.000; 524/502.000; 524/503.000; 525/245.000; 525/298.000; 525/445.000; 525/502.000
	ECLA	C09J201/06; H01B001/20; H01L021/60C4; H01L021/60D; H01L023/29P; H05K003/32B2; M08K; M08K; M08L; M08L; M08L
JP 2004128465	IPCI	H05K0003-32 [ICM,7]; C08G0065-40 [ICS,7]; C08G0065-00 [ICS,7,C*]; C09J0004-00 [ICS,7]; C09J0005-00 [ICS,7]; C09J0009-02 [ICS,7]; C09J0009-00 [ICS,7,C*]; C09J0011-06 [ICS,7]; C09J0011-02 [ICS,7,C*]; C09J0133-00 [ICS,7]; C09J0171-10 [ICS,7]; C09J0171-00 [ICS,7,C*]; C09J0201-06 [ICS,7]; C09J0201-00 [ICS,7,C*]; H01B0001-20 [ICS,7]; H01R0011-01 [ICS,7]
	IPCR	C08G0065-00 [I,C*]; C08G0065-40 [I,A]; C09J0004-00 [I,A]; C09J0004-00 [I,C*]; C09J0005-00 [I,A]; C09J0005-00 [I,C*]; C09J0009-00 [I,C*]; C09J0009-02 [I,A]; C09J0011-02 [I,C*]; C09J0011-06 [I,A]; C09J0133-00 [I,A]; C09J0133-00 [I,C*]; C09J0171-00 [I,C*]; C09J0171-10 [I,A]; C09J0201-00 [I,C*]; C09J0201-06 [I,A]; H01B0001-20 [I,A]; H01B0001-20 [I,C*]; H01R0011-01 [I,A]; H01R0011-01 [I,C*]; H05K0003-32 [I,A]; H05K0003-32 [I,C*]
	FTERM	4J005/AA24; 4J005/BD03; 4J040/DF011; 4J040/DF012; 4J040/DF031; 4J040/DF032; 4J040/DF081; 4J040/DF082; 4J040/EE061; 4J040/GA05; 4J040/GA07; 4J040/GA11; 4J040/HA026; 4J040/HA066; 4J040/HB41; 4J040/HD23; 4J040/JB02; 4J040/KA16; 4J040/KA32; 4J040/LA01; 4J040/LA07; 4J040/LA08; 4J040/LA09; 4J040/NA19; 4J040/NA20; 5E319/AA03; 5E319/AC02; 5E319/AC04; 5E319/BB11; 5G301/DA05; 5G301/DA10; 5G301/DA29; 5G301/DA42; 5G301/DD03
US 20040222408	IPCI	H01C0001-00 [ICM,7]
	IPCR	H01B0001-20 [I,C*]; H01B0001-20 [I,A]; H01L0021-02 [I,C*]; H01L0021-60 [I,A]; H01L0023-28 [I,C*]; H01L0023-29 [I,A]; H05K0003-32 [I,C*]; H05K0003-32 [I,A]
	NCL	252/500.000; 257/E21.511; 257/E21.514; 257/E23.119
	ECLA	H01B001/20; H01L021/60C4; H01L021/60D; H01L023/29P; H05K003/32B2
JP 2005298828	IPCI	C09J0004-00 [I,A]; C08F0283-06 [I,A]; C08F0283-00 [I,C*]; C09J0007-00 [I,A]; C09J0009-02 [I,A];

		C09J0009-00 [I,C*]; C09J0171-10 [I,A]; C09J0171-00 [I,C*]; C09J0201-06 [I,A]; C09J0201-08 [I,A]; C09J0201-00 [I,C*]; H01B0001-20 [I,A]; H01R0011-01 [I,A]
	IPCR	C08F0283-00 [I,C*]; C08F0283-06 [I,A]; C09J0004-00 [I,A]; C09J0004-00 [I,C*]; C09J0007-00 [I,A]; C09J0007-00 [I,C*]; C09J0009-00 [I,C*]; C09J0009-02 [I,A]; C09J0171-00 [I,C*]; C09J0171-10 [I,A]; C09J0201-00 [I,C*]; C09J0201-06 [I,A]; C09J0201-08 [I,A]; H01B0001-20 [I,A]; H01B0001-20 [I,C*]; H01R0011-01 [I,A]; H01R0011-01 [I,C*]
	FTERM	4J004/AA10; 4J004/AA12; 4J004/AA13; 4J004/AA15; 4J004/AA16; 4J004/AB05; 4J004/BA02; 4J004/FA05; 4J026/AA28; 4J026/AB01; 4J026/AB04; 4J026/AB07; 4J026/AB19; 4J026/AB28; 4J026/BA27; 4J026/BA28; 4J026/BA30; 4J026/BA40; 4J026/DB15; 4J026/GA08; 4J040/EE06; 4J040/FA10; 4J040/FA13; 4J040/FA14; 4J040/FA15; 4J040/FA18; 4J040/FA21; 4J040/FA23; 4J040/FA25; 4J040/FA26; 4J040/FA27; 4J040/FA28; 4J040/FA30; 4J040/HB41; 4J040/KA12; 4J040/KA16; 4J040/LA09; 4J040/NA19; 4J040/NA20; 5G301/DA05; 5G301/DA10; 5G301/DA29; 5G301/DA42; 5G301/DD03; 5G301/DD08
JP 2005307210	IPCI	C09J0007-00 [ICM,7]; C09J0009-02 [ICS,7]; C09J0009-00 [ICS,7,C*]; C09J0011-04 [ICS,7]; C09J0011-06 [ICS,7]; C09J0011-02 [ICS,7,C*]; C09J0109-00 [ICS,7]; C09J0109-02 [ICS,7]; C09J0113-00 [ICS,7]; C09J0133-02 [ICS,7]; C09J0171-10 [ICS,7]; C09J0171-00 [ICS,7,C*]; C09J0175-04 [ICS,7]; H01B0001-20 [ICS,7]; H01B0005-16 [ICS,7]; H05K0003-32 [ICS,7]; H05K0003-36 [ICS,7]
	FTERM	4J004/AA05; 4J004/AA10; 4J004/AA11; 4J004/AA14; 4J004/AB05; 4J004/BA02; 4J004/EA07; 4J004/FA05; 4J040/CA071; 4J040/CA101; 4J040/DF011; 4J040/EE061; 4J040/EF351; 4J040/EK031; 4J040/FA13; 4J040/FA14; 4J040/GA07; 4J040/HA066; 4J040/HB41; 4J040/JA09; 4J040/JB02; 4J040/KA11; 4J040/LA01; 4J040/LA05; 4J040/LA06; 4J040/LA09; 4J040/MA02; 4J040/NA19; 5E319/AA03; 5E319/AA07; 5E319/AB06; 5E319/AC01; 5E319/BB16; 5E319/CC12; 5E319/CD26; 5E319/GG15; 5E344/AA01; 5E344/AA22; 5E344/BB02; 5E344/CC21; 5E344/CD04; 5E344/DD06; 5E344/EE21; 5G301/DA03; 5G301/DA05; 5G301/DA12; 5G301/DA42; 5G301/DA59; 5G301/DA60; 5G301/DD03; 5G307/HA03; 5G307/HB03; 5G307/HC01; 5G307/HC02
JP 2005314696	IPCI	C09J0007-00 [ICM,7]; C09J0004-00 [ICS,7]; C09J0005-00 [ICS,7]; C09J0009-02 [ICS,7]; C09J0009-00 [ICS,7,C*]; C09J0011-06 [ICS,7]; C09J0011-02 [ICS,7,C*]; C09J0201-06 [ICS,7]; C09J0201-00 [ICS,7,C*]; H01B0001-20 [ICS,7]; H01B0005-16 [ICS,7]; H01R0011-01 [ICS,7]; H01R0043-00 [ICS,7]; H05K0001-14 [ICS,7]; H05K0003-32 [ICS,7]
	FTERM	4J004/AA01; 4J004/AA08; 4J004/AA12; 4J004/AA13; 4J004/AA15; 4J004/AA16; 4J004/AB05; 4J004/BA02; 4J004/DB02; 4J004/FA05; 4J040/CA072; 4J040/DD062; 4J040/DF002; 4J040/EB032; 4J040/EC002; 4J040/ED002; 4J040/EE062; 4J040/EG002; 4J040/FA101; 4J040/FA131; 4J040/FA21; 4J040/GA05; 4J040/GA07; 4J040/GA11;

		4J040/GA13; 4J040/HA06; 4J040/HB36; 4J040/HB41; 4J040/JA09; 4J040/JB02; 4J040/KA12; 4J040/KA32; 4J040/LA09; 4J040/MB03; 4J040/NA19; 4J040/PA23; 5E051/CA03; 5E319/AA03; 5E319/AC01; 5E319/BB16; 5E319/GG15; 5E344/AA01; 5E344/BB02; 5E344/CD04; 5E344/CD06; 5E344/DD06; 5E344/EE21; 5G301/DA03; 5G301/DA05; 5G301/DA06; 5G301/DA10; 5G301/DA18; 5G301/DA57; 5G301/DD03; 5G301/DD08; 5G307/HA02; 5G307/HB01; 5G307/HB03; 5G307/HC01
JP 2005333119	IPCI	H01L0021-60 [I,A]; H01L0021-02 [I,C*]; C09J0005-06 [I,A]; C09J0007-00 [I,A]; C09J0009-02 [I,A]; C09J0009-00 [I,C*]; C09J0011-04 [I,A]; C09J0011-02 [I,C*]; C09J0201-06 [I,A]; C09J0201-00 [I,C*]; H05K0003-32 [I,A]; H01B0001-22 [N,A]
	IPCR	C09J0007-00 [I,C*]; C09J0007-00 [I,A]; H01L0021-02 [I,C]; H01L0021-60 [I,A]; C09J0005-06 [I,C]; C09J0005-06 [I,A]; C09J0009-00 [I,C]; C09J0009-02 [I,A]; C09J0011-02 [I,C]; C09J0011-04 [I,A]; C09J0201-00 [I,C]; C09J0201-06 [I,A]; H01B0001-22 [I,C*]; H01B0001-22 [I,A]; H01R0011-01 [I,C*]; H01R0011-01 [I,A]; H05K0003-32 [I,C]; H05K0003-32 [I,A]
	FTERM	4J004/AA01; 4J004/AA13; 4J004/AB05; 4J004/BA03; 4J004/FA05; 4J040/EC061; 4J040/FA132; 4J040/FA212; 4J040/HA066; 4J040/HB41; 4J040/JA09; 4J040/JB02; 4J040/JB10; 4J040/KA03; 4J040/KA11; 4J040/KA16; 4J040/KA18; 4J040/KA32; 4J040/LA09; 4J040/MA02; 4J040/NA20; 4J040/PB05; 4J040/PB08; 5E319/AA03; 5E319/AB05; 5E319/AC01; 5E319/BB16; 5E319/CC12; 5E319/CC61; 5E319/CD26; 5E319/GG15; 5F044/LL09; 5F044/RR17; 5G301/DA03; 5G301/DA05; 5G301/DA06; 5G301/DA10; 5G301/DA11; 5G301/DA12; 5G301/DA13; 5G301/DA18; 5G301/DA42; 5G301/DD03
US 20060014860	IPCI	C08K0005-00 [I,A]
	IPCR	C08K0005-00 [I,A]; C08K0005-00 [I,C]
	NCL	523/457.000
	ECLA	C08G018/32A2; C08G018/08B6C; C08G018/28D6H; C08G018/38F3; C08G018/67B4+18/08B6C; C08G018/67B4+18/80B3D2C; C09D005/24; C09D175/16+B4B; M08K; M08K
US 20060060969	IPCI	H01L0023-52 [I,A]
	IPCR	H01L0023-52 [I,A]; H01L0023-52 [I,C]
	NCL	257/746.000
	ECLA	C08G018/32A2; C08G018/08B6C; C08G018/28D6H; C08G018/38F3; C08G018/67B4+18/08B6C; C08G018/67B4+18/80B3D2C; C09D005/24; C09D175/16+B4B; M08K; M08K
US 20060063366	IPCI	H01L0021-44 [I,A]; H01L0021-02 [I,C*]
	IPCR	H01L0021-02 [I,C]; H01L0021-44 [I,A]
	NCL	438/613.000
	ECLA	C08G018/32A2; C08G018/08B6C; C08G018/28D6H; C08G018/38F3; C08G018/67B4+18/08B6C; C08G018/67B4+18/80B3D2C; C09D005/24; C09D175/16+B4B; M08K; M08K
US 20070299172	IPCI	C08K0005-521 [I,A]; C08K0005-00 [I,C*]
	NCL	524/145.000; 524/115.000
	ECLA	M08L; M08L
US 20080054225	IPCI	H01B0001-00 [I,A]; C08F0283-00 [I,A]

NCL 252/500.000; 525/418.000; 525/451.000
ECLA M08L; M08L

AB The invention concerns a circuit connecting material to be interposed between circuit electrodes facing each other and, when the facing electrodes are pressed against each other, to elec. connect the electrodes in the pressing direction, which comprises as the essential ingredients (1) a hardener generating free radicals upon heating, (2) a hydroxylated resin having a mol. weight of 10,000 or higher, and (3) a radical-polymerizable substance; and a structure and method of connecting a circuit terminal by using the material. Mixing a 40% solution of PKHC (phenoxy resin) in PhMe/vinyl acetate mixture, 50, with Epolite 80MFA 50 and Percure HO (a peroxide) 5 g, combining the mixture with 3 vol% Ni-plated polystyrene particles as elec. conductors, coating on a 80-μm PET polyester film and drying at 70° for 10 min gave an adhesive film for adhering flexible circuit board.

ST elec circuit board adhering adhesive film; phenoxy resin adhesive radical polymn crosslinker; hydroxylated resin adhesive circuit board; conductive adhesive elec circuit bonding

IT Synthetic rubber, uses
RL: POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); USES (Uses)
(acrylonitrile-butadiene-methacrylic acid, blend, Nipol 1072; circuit connecting materials, and structure and method of connecting circuit terminal)

IT Nitrile rubber, uses
RL: POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); USES (Uses)
(carboxy-terminated, blend, Hycar CTBNX 1009SP; circuit connecting materials, and structure and method of connecting circuit terminal)

IT Printed circuit boards
(circuit connecting materials, and structure and method of connecting circuit terminal)

IT Acrylic rubber
Phenoxy resins
RL: POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); USES (Uses)
(circuit connecting materials, and structure and method of connecting circuit terminal)

IT Adhesives
(conductive; circuit connecting materials, and structure and method of connecting circuit terminal)

IT Adhesive films
(elec. conductive; circuit connecting materials, and structure and method of connecting circuit terminal)

IT Polymerization catalysts
(radical; in circuit connecting materials, and structure and method of connecting circuit terminal)

IT 136662-27-6, Percure HO
RL: CAT (Catalyst use); USES (Uses)
(circuit connecting materials, and structure and method of connecting circuit terminal)

IT 79-10-7D, 2-Propenoic acid, esters with phosphoric acid and glycol, uses
7664-38-2D, Phosphoric acid, esters with acrylic acid and glycol, uses
25068-38-6, PKHC 120123-31-1, Trihydroxyethyl glycol dimethacrylate homopolymer 214419-12-2 214419-26-8 214419-47-3
214419-51-9 214419-52-0
RL: POF (Polymer in formulation); PRP (Properties); TEM (Technical or

engineered material use); USES (Uses)
(circuit connecting materials, and structure and method of connecting circuit terminal)
IT 9003-53-6, Polystyrene
RL: TEM (Technical or engineered material use); USES (Uses)
(nickel-plated powder, elec. conductors; in circuit connecting materials, and structure and method of connecting circuit terminal)
IT 9003-18-3
RL: POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); USES (Uses)
(nitrile rubber, carboxy-terminated, blend, Hycar CTBNX 1009SP; circuit connecting materials, and structure and method of connecting circuit terminal)
IT 7440-02-0, Nickel, uses
RL: TEM (Technical or engineered material use); USES (Uses)
(on polystyrene powder, elec. conductors; in circuit connecting materials, and structure and method of connecting circuit terminal)
RE.CNT 5 THERE ARE 5 CITED REFERENCES AVAILABLE FOR THIS RECORD
RE
(1) Fuji Polymer Industries Co Ltd; JP 06295617 A 1994 CAPLUS
(2) Soken Chemical Engineering Co Ltd; JP 08325543 A 1996 CAPLUS
(3) Sumitomo Bakelite Co Ltd; JP 09169958 A 1997 CAPLUS
(4) Sumitomo Bakelite Co Ltd; JP 09291259 A 1997 CAPLUS
(5) Sumitomo Bakelite Co Ltd; JP 995652 A 1997

=> d his

(FILE 'HOME' ENTERED AT 14:17:34 ON 01 JUN 2009)

FILE 'REGISTRY' ENTERED AT 14:17:54 ON 01 JUN 2009
L1 2 S 42594-17-2 OR 40220-08-4 OR 64401-02-8 OR 024650-42-8 OR 7598
L2 4 S 42594-17-2 OR 40220-08-4 OR 64401-02-8 OR 024650-42-8 OR 7598
L3 6 S SARTOMER 349
L4 1 S SARTOMER 349/CN
L5 1 S IRGACURE 651/CN
L6 1 S 42594-17-2/CRN AND 40220-08-4/CRN AND 24447-78-7/CRN
L7 1 S EBECRYL 8402/CN

FILE 'CAPLUS' ENTERED AT 14:25:03 ON 01 JUN 2009
L8 1 S L6
S 42594-17-2/CRN AND 40220-08-4/CRN AND 24447-78-7/CRN

FILE 'REGISTRY' ENTERED AT 14:25:42 ON 01 JUN 2009
L9 279 S 24447-78-7/CRN

FILE 'CAPLUS' ENTERED AT 14:25:43 ON 01 JUN 2009
L10 220 S L9

FILE 'REGISTRY' ENTERED AT 14:25:43 ON 01 JUN 2009
L11 1033 S 40220-08-4/CRN

FILE 'CAPLUS' ENTERED AT 14:25:43 ON 01 JUN 2009
L12 800 S L11

FILE 'REGISTRY' ENTERED AT 14:25:44 ON 01 JUN 2009
L13 1064 S 42594-17-2/CRN

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     FILE 'CAPLUS' ENTERED AT 14:25:44 ON 01 JUN 2009
L14          736 S L13
L15            2 S L14 AND L12 AND L10

=> s thiol and curl
         61650 THIOL
          4823 CURL
L16            5 THIOL AND CURL

=> d all 1-5

L16  ANSWER 1 OF 5  CAPLUS  COPYRIGHT 2009 ACS on STN
AN   2009:86515  CAPLUS
DN   150:169806
ED   Entered STN:  23 Jan 2009
TI   Urethane bond-containing acrylic curable compositions with good
     curability, surface hardness, abrasion resistance, flexibility, bending
     property, and transparency
IN   Urakawa, Yoshifumi; Ishii, Nobuaki; Tomita, Miyuki; Hattori, Yotaro;
     Ikeda, Haruhiko; Murofushi, Katsumi
PA   Showa Denko K.K., Japan
SO   PCT Int. Appl., 42pp.
     CODEN: PIXXD2
DT   Patent
LA   Japanese
CC   38-3 (Plastics Fabrication and Uses)
     Section cross-reference(s): 42, 74
FAN.CNT 1
     PATENT NO.          KIND   DATE        APPLICATION NO.        DATE
     ---------------     ----   --------    --------------------   --------
PI   WO 2009011211        A1    20090122    WO 2008-JP61636        20080626
         W:  AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ,
             CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES,
             FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE,
             KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD,
             ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH,
             PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM,
             TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW
         RW: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU,
             IE, IS, IT, LT, LU, LV, MC, MT, NL, NO, PL, PT, RO, SE, SI, SK,
             TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD,
             TG, BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW,
             AM, AZ, BY, KG, KZ, MD, RU, TJ, TM
PRAI JP 2007-184230       A     20070713
     JP 2008-113743       A     20080424
CLASS
 PATENT NO.      CLASS  PATENT FAMILY CLASSIFICATION CODES
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 WO 2009011211   IPCI   C08G0075-04 [I,A]; C08G0075-00 [I,C*]; C09D0007-12
                        [I,A]; C09D0175-14 [I,A]; C09J0011-06 [I,A];
                        C09J0011-02 [I,C*]; C09J0175-14 [I,A]; G02B0001-04
                        [I,A]
AB   Title curable compns. comprise a urethane compound
     CH2:CHR3OCOR1OOCNHR2OOCCHR4:CH2, a thiol compound, and a polymerization
     initiator, wherein R1 = linear or branched divalent aliphatic group, divalent
     organic group having alicyclic or aromatic ring, or [(CH2)aO(CH2)b]c; a, b =
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independently 1-10 integer; c = 1-5 integer; R2 = linear or branched divalent aliphatic group, divalent organic group having alicyclic or aromatic ring, or [(CH2)dO(CH2)e]f; d, e = independently 1-10 integer; f = 1-5 integer; and R3, R4 = independently H or Me. Thus, 100 parts 2-hydroxyethyl acrylate and 122 parts Karenz AOI were reacted in the presence of 2,6-di-tert-butyl-4-methylphenol to give a urethane bond-containing acrylic monomer, 98 parts of which was mixed with 2 parts Karenz MT PE 1 and 2 parts Irgacure 184, the resulting composition was applied on a glass substrate and irradiated with a high pressure mercury lamp to give a test piece, showing pencil hardness 3H, light transmittance 98.4%, good curability, and low curl.

ST urethane bond contg acrylic curable compn curability surface hardness; abrasion resistance flexibility bending property transparency; hydroxyethyl acrylate Karenz reaction; oxopropenyloxyethylaminocarbonyloxyethyl acrylate prepn; thiol compd oxopropenyloxyethylaminocarbonyloxyethyl acrylate homopolymer coating

IT Coating materials
(abrasion-resistant, anticorrosive; urethane bond-containing acrylic curable compns.)

IT Polyurethanes, uses
RL: IMF (Industrial manufacture); POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(acrylic; urethane bond-containing acrylic curable compns.)

IT Transparent materials
(adhesives; urethane bond-containing acrylic curable compns.)

IT Transparent materials
(coatings; urethane bond-containing acrylic curable compns.)

IT Acrylic polymers, uses
RL: IMF (Industrial manufacture); POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(polyurethane-; urethane bond-containing acrylic curable compns.)

IT Adhesives
Coating materials
(transparent; urethane bond-containing acrylic curable compns.)

IT Optical films
(urethane bond-containing acrylic curable compns.)

IT Acrylic polymers, uses
RL: IMF (Industrial manufacture); POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(urethane bond-containing acrylic curable compns.)

IT Thiols, uses
RL: MOA (Modifier or additive use); USES (Uses)
(urethane bond-containing acrylic curable compns.)

IT 117804-97-4P 325147-27-1P 662112-57-4P
RL: IMF (Industrial manufacture); RCT (Reactant); PREP (Preparation); RACT (Reactant or reagent)
(monomer; urethane bond-containing acrylic curable compns.)

IT 119591-68-3P 325147-30-6P 1103459-28-4P 1103459-31-9P 1104518-05-9P
RL: IMF (Industrial manufacture); POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(urethane bond-containing acrylic curable compns.)
IT 31775-89-0, Karenz MT PE 1 594836-83-6, Karenz MT BD 1
RL: MOA (Modifier or additive use); USES (Uses)
(urethane bond-containing acrylic curable compns.)
IT 818-61-1, 2-Hydroxyethyl acrylate 868-77-9, 2-Hydroxyethyl methacrylate
13641-96-8, Karenz AOI 30674-80-7, Karenz MOI
RL: RCT (Reactant); RACT (Reactant or reagent)
(urethane bond-containing acrylic curable compns.)
RE.CNT 6 THERE ARE 6 CITED REFERENCES AVAILABLE FOR THIS RECORD
RE
(1) Dainippon Ink And Chemicals Inc; JP 200140039 A 2001
(2) Mitsubishi Rayon Co Ltd; JP 63-199210 A 1988 CAPLUS
(3) Mitsubishi Rayon Co Ltd; JP 2003221420 A 2003 CAPLUS
(4) Nippon Kayaku Co Ltd; JP 2004238481 A 2004 CAPLUS
(5) Showa Denko Kabushiki Kaisha; JP 63-234032 A 1988 CAPLUS
(6) Showa Denko Kabushiki Kaisha; WO 2007086461 A1 2007 CAPLUS

L16 ANSWER 2 OF 5 CAPLUS COPYRIGHT 2009 ACS on STN
AN 2006:1229462 CAPLUS
DN 146:12560
ED Entered STN: 24 Nov 2006
TI Hair treatment preparations containing acidic thiols as curl reinforcing agents
IN Fujii, Masashi; Fujii, Toshifumi
PA Japan
SO Jpn. Kokai Tokkyo Koho, 7pp.
CODEN: JKXXAF
DT Patent
LA Japanese
CC 62-3 (Essential Oils and Cosmetics)
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 2006315976	A	20061124	JP 2005-138634	20050511
PRAI JP 2005-138634		20050511		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
JP 2006315976	IPCI	A61K0008-00 [I,A]; A61Q0005-04 [I,A]
	IPCR	A61K0008-00 [I,C]; A61K0008-00 [I,A]; A61Q0005-04 [I,C]; A61Q0005-04 [I,A]
	FTERM	4C083/AC112; 4C083/AC122; 4C083/AC542; 4C083/AC771; 4C083/AC772; 4C083/AC781; 4C083/AC782; 4C083/AC851; 4C083/CC34; 4C083/DD23; 4C083/DD27; 4C083/EE25

AB This invention relates to a curl-enhancing agent in permanent wave treatment which contains ≥ 2 thiol groups and ≥ 1 acidic group (carboxylic acid, phosphoric acid ester, sulfonic acid, sulfuric acid ester group). For example, a curl-enhancing solution contained dithioerythritol monosulfate 4, triethanolamine 0.5, perfumes q.s., and purified water balance to 100 %.
ST hair permanent wave enhancer acidic polythiol; dithioerythritol sulfate hair permanent curl enhancer
IT Permanent wave-setting preparations
(hair treatment prepns. containing acidic thiols as curl reinforcing agents)
IT 59-52-9, 2,3-Dimercapto-1-propanol 74-61-3 304-55-2, meso-2,3-Dimercaptosuccinic acid 496-74-2,

1,2-Dimercapto-4-methylbenzene 540-63-6, 1,2-Dimercaptoethane 624-39-5, 1,4-Benzenedithiol 626-04-0, Dithioresorcinol 638-16-4, Trithiocyanuric acid 814-67-5, 1,2-Dimercaptopropane 928-98-3, 1,5-Pentanedithiol 1072-71-5, Bismuthiol 1077-28-7, Thioctic acid 1191-08-8, 1,4-Dimercaptobutane 1191-43-1, 1,6-Hexanedithiol 2001-93-6, Dithiouracil 3483-12-3, DL-Dithiothreitol 5325-88-2, 1,5-Dimercaptonaphthalene 5437-25-2, 2,6-Purinedithiol 6892-68-8, Dithioerythritol 14970-87-7, 3,6-Dioxa-1,8-octanedithiol 16096-97-2, L-Dithiothreitol 75464-52-7, 2,5-Diamino-1,4-benzenedithiol dihydrochloride 915392-65-3
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(hair treatment prepns. containing acidic thiols as curl reinforcing agents)

L16 ANSWER 3 OF 5 CAPLUS COPYRIGHT 2009 ACS on STN
AN 2005:582516 CAPLUS
DN 143:98506
ED Entered STN: 07 Jul 2005
TI Polyimide based adhesive compositions useful in flexible circuit applications, and compositions and methods relating thereto
IN Dueber, Thomas E.; West, Michael W. J.; Auman, Brian C.; Kasowski, Robert V.
PA E.I. Du Pont de Nemours and Company, USA
SO Eur. Pat. Appl., 17 pp.
CODEN: EPXXDW
DT Patent
LA English
IC ICM C08L083-14
ICS C08K005-00
CC 38-3 (Plastics Fabrication and Uses)
Section cross-reference(s): 76
FAN.CNT 2

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	EP 1550698	A2	20050706	EP 2004-27062	20041115
	EP 1550698	A3	20060208		
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, PL, SK, HR, IS, YU				
	JP 2005194527	A	20050721	JP 2004-372026	20041222
PRAI	US 2003-533468P	P	20031230		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
EP 1550698	ICM	C08L083-14
	ICS	C08K005-00
	IPCI	C08L0083-14 [I,A]; C08L0083-00 [I,C*]; C08K0005-00 [I,A]
	IPCR	C08L0079-00 [I,C*]; C08L0079-08 [I,A]; C08L0083-00 [I,C]; C08L0083-14 [I,A]; B32B0027-08 [I,C*]; B32B0027-08 [I,A]; B32B0027-18 [I,C*]; B32B0027-18 [I,A]; C08G0065-00 [I,C*]; C08G0065-336 [I,A]; C08G0077-00 [I,C*]; C08G0077-455 [I,A]; C08K0005-00 [I,C]; C08K0005-00 [I,A]; C08K0005-34 [N,A]; C08L0063-00 [I,C*]; C08L0063-00 [I,A]; C08L0071-00 [I,C*]; C08L0071-02 [I,A]; C08L0083-10 [I,A]; C09D0183-10 [I,C*]; C09D0183-10 [I,A]; C09J0007-00

		[I,C*]; C09J0007-00 [I,A]; C09J0011-00 [I,C*]; C09J0011-00 [I,A]; C09J0179-00 [I,C*]; C09J0179-08 [I,A]; C09J0183-00 [I,C*]; C09J0183-10 [I,A]; H01L0021-02 [I,C*]; H01L0021-60 [I,A]; H05K0001-00 [N,C*]; H05K0001-00 [N,A]; H05K0001-03 [I,C*]; H05K0001-03 [I,A]; H05K0003-28 [I,C*]; H05K0003-28 [I,A]; H05K0003-38 [I,C*]; H05K0003-38 [I,A]; H05K0003-46 [I,C*]; H05K0003-46 [I,A]
	ECLA	B32B027/08; B32B027/18; C08G065/336; C08G077/455; C08K005/00P8+L83/14; C08L063/00+B4Z; C08L071/02+B4Z; C08L083/10+B4; C09D183/10; H05K001/03C2E; H05K003/38D; M08K; M08L; T05K; T05K; T05K; T05K; T05K
JP 2005194527	IPCI	C08L0079-08 [ICM,7]; C08L0079-00 [ICM,7,C*]; C09J0007-00 [ICS,7]; C09J0011-00 [ICS,7]; C09J0179-08 [ICS,7]; C09J0179-00 [ICS,7,C*]; C09J0183-10 [ICS,7]; C09J0183-00 [ICS,7,C*]; H01L0021-60 [ICS,7]; H01L0021-02 [ICS,7,C*]; H05K0001-03 [ICS,7]; H05K0003-28 [ICS,7]; H05K0003-46 [ICS,7]
	IPCR	C08L0079-00 [I,C*]; C08L0079-08 [I,A]; B32B0027-08 [I,C*]; B32B0027-08 [I,A]; B32B0027-18 [I,C*]; B32B0027-18 [I,A]; C08G0065-00 [I,C*]; C08G0065-336 [I,A]; C08G0077-00 [I,C*]; C08G0077-455 [I,A]; C08K0005-00 [I,C*]; C08K0005-00 [I,A]; C08K0005-34 [N,A]; C08L0063-00 [I,C*]; C08L0063-00 [I,A]; C08L0071-00 [I,C*]; C08L0071-02 [I,A]; C08L0083-00 [I,C*]; C08L0083-10 [I,A]; C08L0083-14 [I,A]; C09D0183-10 [I,C*]; C09D0183-10 [I,A]; C09J0007-00 [I,C*]; C09J0007-00 [I,A]; C09J0011-00 [I,C*]; C09J0011-00 [I,A]; C09J0179-00 [I,C*]; C09J0179-08 [I,A]; C09J0183-00 [I,C*]; C09J0183-10 [I,A]; H01L0021-02 [I,C*]; H01L0021-60 [I,A]; H05K0001-00 [N,C*]; H05K0001-00 [N,A]; H05K0001-03 [I,C*]; H05K0001-03 [I,A]; H05K0003-28 [I,C*]; H05K0003-28 [I,A]; H05K0003-38 [I,C*]; H05K0003-38 [I,A]; H05K0003-46 [I,C*]; H05K0003-46 [I,A]
	FTERM	4J002/CD052; 4J002/CM041; 4J002/CP171; 4J002/DH057; 4J002/EH096; 4J002/EH146; 4J002/EV286; 4J002/EW046; 4J002/EW047; 4J002/EW157; 4J002/FD026; 4J002/FD137; 4J002/GJ01; 4J004/AA11; 4J004/AB03; 4J004/BA02; 4J004/EA06; 4J004/FA08; 4J040/EH031; 4J040/EK111; 4J040/HD21; 4J040/HD28; 4J040/JA09; 4J040/JB01; 4J040/KA36; 4J040/LA08; 4J040/MA10; 4J040/NA08; 4J040/NA20; 5E314/AA36; 5E314/AA42; 5E314/BB02; 5E314/BB11; 5E314/CC01; 5E314/DD06; 5E314/FF06; 5E314/FF19; 5E314/GG26; 5E346/AA16; 5E346/CC10; 5E346/CC32; 5E346/CC41; 5E346/EE12; 5E346/GG19; 5E346/GG27; 5E346/GG28; 5E346/HH16; 5F044/MM11

AB A low modulus polyimide adhesive composition comprises: i. 100 weight parts low modulus polyimidosiloxane component; ii. a thermosetting substantially-non-halogenated epoxy adjuvant (optionally including an epoxy catalyst) comprising a plurality of epoxy moieties or derivs. of epoxy moieties, being present in a weight part amount within a range between and including any two of the following weight part quantities per 100 parts by weight of the polyimidosiloxane component: 1, 2, 3, 4, 5, 6, 7, 8, 9 10, 12, 15, 18, 20, 25, 30, 35, 38, 40, 42, 45, 47, 48, 49, and 50; comprising less than or equal to 500,100, 50, 25, 10, 5, or 0 ppm halogen; iii. a plasticizer, being present in a weight part amount within a range between and

including any two of the following weight part quantities per 100 parts by weight of the polyimidosiloxane component: 5, 10, 15, 20, 25, 30, 35, 40, 45, 50, 55, 60, 65, 70, 75, and 80, and; iv. an insol. halogen-free flame-retardant filler in an amount of 2-100 parts by weight per 100 parts by weight of the polyimidosiloxane component; , and v. optionally an adhesion promoter. The adhesive can be applied upon (or incorporated into) flexible circuits using a relatively low lamination temperature, generally no higher than 200, 190, 180, 175, 170, 165, 160, 155, or 150°C. The adhesive is generally resistant to unwanted curl even in cases where the adhesive polyimide and the base film polyimide have a coefficient of linear thermal expansions (measured between 50° and 250°C) that differ by more than 10, 15, 20 25, or 30 ppm/°C.

ST polyimidosiloxane epoxy adhesive printed circuit board

IT Polybenzimidazoles
RL: MOA (Modifier or additive use); USES (Uses)
(adhesion promoter; polyimide based adhesive compns. useful in flexible circuit applications)

IT Polyimides, uses
RL: POF (Polymer in formulation); TEM (Technical or engineered material use); USES (Uses)
(di-Me siloxane-polyether-; polyimide based adhesive compns. useful in flexible circuit applications)

IT Polyethers, uses
RL: POF (Polymer in formulation); TEM (Technical or engineered material use); USES (Uses)
(di-Me siloxane-polyimide-; polyimide based adhesive compns. useful in flexible circuit applications)

IT Polysiloxanes, uses
RL: POF (Polymer in formulation); TEM (Technical or engineered material use); USES (Uses)
(di-Me, polyether-polyimide-; polyimide based adhesive compns. useful in flexible circuit applications)

IT Recording materials
(disk drive; polyimide based adhesive compns. useful in flexible circuit applications)

IT Phenolic resins, uses
RL: POF (Polymer in formulation); TEM (Technical or engineered material use); USES (Uses)
(epoxy, novolak; polyimide based adhesive compns. useful in flexible circuit applications)

IT Telephones
(mobile phone; polyimide based adhesive compns. useful in flexible circuit applications)

IT Epoxy resins, uses
RL: POF (Polymer in formulation); TEM (Technical or engineered material use); USES (Uses)
(phenolic, novolak; polyimide based adhesive compns. useful in flexible circuit applications)

IT Adhesives
Computers
Laminated materials
Printed circuit boards
(polyimide based adhesive compns. useful in flexible circuit applications)

IT 1330-78-5, Tricresyl phosphate
RL: TEM (Technical or engineered material use); USES (Uses)
(Lindol XP Plus, flame retardant; polyimide based adhesive compns.

useful in flexible circuit applications)
IT 95-14-7, 1H-Benzotriazole 583-39-1, 2-Mercaptobenzimidazole 1760-24-3, N-2-Aminoethyl-3-aminopropyltrimethoxysilane 2349-67-9, 5-Amino-1,3,4-thiadiazole-2-thiol 2530-83-8, 3-Glycidoxypropyltrimethoxysilane 2530-85-0, 3-Methacryloxypropyltrimethoxysilane 3179-31-5, 3MT 23779-32-0, N-(Triethoxysilylpropyl)urea
RL: MOA (Modifier or additive use); USES (Uses)
(adhesion promoter; polyimide based adhesive compns. useful in flexible circuit applications)
IT 218768-84-4, Melapur 200
RL: TEM (Technical or engineered material use); USES (Uses)
(flame-retardant filler; polyimide based adhesive compns. useful in flexible circuit applications)
IT 108727-35-1, DEN 438EK85
RL: POF (Polymer in formulation); TEM (Technical or engineered material use); USES (Uses)
(polyimide based adhesive compns. useful in flexible circuit applications)
IT 857047-88-2
RL: POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); USES (Uses)
(polyimide; polyimide based adhesive compns. useful in flexible circuit applications)
RE.CNT 2 THERE ARE 2 CITED REFERENCES AVAILABLE FOR THIS RECORD
RE
(1) Anon; EP 0604038 A2 CAPLUS
(2) Anon; US 5935372 A CAPLUS

L16 ANSWER 4 OF 5 CAPLUS COPYRIGHT 2009 ACS on STN
AN 2005:570549 CAPLUS
DN 143:98496
ED Entered STN: 01 Jul 2005
TI Polyimide based adhesive compositions useful in flexible circuit applications, compositions, and fabrication of laminate for electronic device
IN Dueber, Thomas E.; West, Michael W.; Auman, Brian C.; Kasowski, Robert V.
PA E. I. Du Pont De Nemours and Company, USA
SO U.S. Pat. Appl. Publ., 13 pp.
CODEN: USXXCO
DT Patent
LA English
IC ICM C08L063-00
ICS C08L083-04
INCL 525476000
CC 38-3 (Plastics Fabrication and Uses)
Section cross-reference(s): 37, 76
FAN.CNT 2

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 20050143534	A1	20050630	US 2004-892863	20040716
	US 7220490	B2	20070522		
	JP 2005194527	A	20050721	JP 2004-372026	20041222
PRAI	US 2003-533468P	P	20031230		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES

US 20050143534	ICM	C08L063-00
	ICS	C08L083-04
	INCL	525476000
	IPCI	B32B0009-04 [I,A]
	IPCR	C08L0063-00 [I,C*]; C08L0063-00 [I,A]; C08L0083-00 [I,C*]; C08L0083-04 [I,A]; B32B0009-04 [I,C]; B32B0009-04 [I,A]
	NCL	525/476.000; 428/447.000; 525/431.000
JP 2005194527	IPCI	C08L0079-08 [ICM,7]; C08L0079-00 [ICM,7,C*]; C09J0007-00 [ICS,7]; C09J0011-00 [ICS,7]; C09J0179-08 [ICS,7]; C09J0179-00 [ICS,7,C*]; C09J0183-10 [ICS,7]; C09J0183-00 [ICS,7,C*]; H01L0021-60 [ICS,7]; H01L0021-02 [ICS,7,C*]; H05K0001-03 [ICS,7]; H05K0003-28 [ICS,7]; H05K0003-46 [ICS,7]
	IPCR	C08L0079-00 [I,C*]; C08L0079-08 [I,A]; B32B0027-08 [I,C*]; B32B0027-08 [I,A]; B32B0027-18 [I,C*]; B32B0027-18 [I,A]; C08G0065-00 [I,C*]; C08G0065-336 [I,A]; C08G0077-00 [I,C*]; C08G0077-455 [I,A]; C08K0005-00 [I,C*]; C08K0005-00 [I,A]; C08K0005-34 [N,A]; C08L0063-00 [I,C*]; C08L0063-00 [I,A]; C08L0071-00 [I,C*]; C08L0071-02 [I,A]; C08L0083-00 [I,C*]; C08L0083-10 [I,A]; C08L0083-14 [I,A]; C09D0183-10 [I,C*]; C09D0183-10 [I,A]; C09J0007-00 [I,C*]; C09J0007-00 [I,A]; C09J0011-00 [I,C*]; C09J0011-00 [I,A]; C09J0179-00 [I,C*]; C09J0179-08 [I,A]; C09J0183-00 [I,C*]; C09J0183-10 [I,A]; H01L0021-02 [I,C*]; H01L0021-60 [I,A]; H05K0001-00 [N,C*]; H05K0001-00 [N,A]; H05K0001-03 [I,C*]; H05K0001-03 [I,A]; H05K0003-28 [I,C*]; H05K0003-28 [I,A]; H05K0003-38 [I,C*]; H05K0003-38 [I,A]; H05K0003-46 [I,C*]; H05K0003-46 [I,A]
	FTERM	4J002/CD052; 4J002/CM041; 4J002/CP171; 4J002/DH057; 4J002/EH096; 4J002/EH146; 4J002/EV286; 4J002/EW046; 4J002/EW047; 4J002/EW157; 4J002/FD026; 4J002/FD137; 4J002/GJ01; 4J004/AA11; 4J004/AB03; 4J004/BA02; 4J004/EA06; 4J004/FA08; 4J040/EH031; 4J040/EK111; 4J040/HD21; 4J040/HD28; 4J040/JA09; 4J040/JB01; 4J040/KA36; 4J040/LA08; 4J040/MA10; 4J040/NA08; 4J040/NA20; 5E314/AA36; 5E314/AA42; 5E314/BB02; 5E314/BB11; 5E314/CC01; 5E314/DD06; 5E314/FF06; 5E314/FF19; 5E314/GG26; 5E346/AA16; 5E346/CC10; 5E346/CC32; 5E346/CC41; 5E346/EE12; 5E346/GG19; 5E346/GG27; 5E346/GG28; 5E346/HH16; 5F044/MM11

AB The low modulus polyimide adhesive comps. contain a low modulus polyimidosiloxane polymer, a thermosetting substantially-nonhalogenated epoxy (optionally including an epoxy catalyst), a plasticizer, an insol. halogen-free flame-retardant filler, and optionally an adhesion promoter. The adhesive can be applied upon (or incorporated into) flexible circuits using a relatively low lamination temperature, generally ≤200, 190, 180, 175, 170, 165, 160, 155, or 150°C. The adhesive is generally resistant to unwanted curl even in cases where the adhesive polyimide and the base film polyimide have a coefficient of linear thermal expansion (measured 50-250°C) that differ by >10, 15, 20 25, or 30 ppm/°C.

ST polyimide siloxane blend epoxy adhesive flexible circuit; coverlay film polyimide based flexible circuit

IT Polybenzimidazoles

RL: MOA (Modifier or additive use); USES (Uses)
(adhesion promoter; polyimide based adhesive compns. useful in fabrication of curl-resistant laminate for electronic device and applied at moderate temperature)

IT Magnetic disks
(hard; polyimide based adhesive compns. useful in fabrication of curl-resistant laminate for electronic device and applied at moderate temperature)

IT Telephones
(mobile phone; polyimide based adhesive compns. useful in fabrication of curl-resistant laminate for electronic device and applied at moderate temperature)

IT Polyimides, miscellaneous
RL: MSC (Miscellaneous)
(polyether-, substrate; polyimide based adhesive compns. useful in fabrication of curl-resistant laminate for electronic device and applied at moderate temperature)

IT Adhesion promoters
Computers
Fillers
Fireproofing agents
Plasticizers
Printed circuit boards
(polyimide based adhesive compns. useful in fabrication of curl -resistant laminate for electronic device and applied at moderate temperature)

IT Polyamic acids
RL: IMF (Industrial manufacture); RCT (Reactant); PREP (Preparation); RACT (Reactant or reagent)
(polyimide based adhesive compns. useful in fabrication of curl -resistant laminate for electronic device and applied at moderate temperature)

IT Epoxy resins, uses
RL: POF (Polymer in formulation); TEM (Technical or engineered material use); USES (Uses)
(polyimide based adhesive compns. useful in fabrication of curl -resistant laminate for electronic device and applied at moderate temperature)

IT Polyethers, miscellaneous
RL: MSC (Miscellaneous)
(polyimide-, substrate; polyimide based adhesive compns. useful in fabrication of curl-resistant laminate for electronic device and applied at moderate temperature)

IT Polysiloxanes, uses
RL: IMF (Industrial manufacture); POF (Polymer in formulation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(polyimide-; polyimide based adhesive compns. useful in fabrication of curl-resistant laminate for electronic device and applied at moderate temperature)

IT Polyimides, uses
RL: IMF (Industrial manufacture); POF (Polymer in formulation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(polysiloxane-; polyimide based adhesive compns. useful in fabrication of curl-resistant laminate for electronic device and applied at moderate temperature)

IT Adhesives
(sheets; polyimide based adhesive compns. useful in fabrication of

curl-resistant laminate for electronic device and applied at moderate temperature)
IT 1330-78-5, Tricresyl phosphate
RL: MOA (Modifier or additive use); USES (Uses)
(Lindol XP Plus; polyimide based adhesive compns. useful in fabrication of curl-resistant laminate for electronic device and applied at moderate temperature)
IT 95-14-7, 1H-Benzotriazole 583-39-1, 2-Mercaptobenzimidazole 1760-24-3, N-2-Aminoethyl-3-aminopropyltrimethoxysilane 2349-67-9, 5-Amino-1,3,4-thiadiazole-2-thiol 2530-83-8, 3-Glycidoxypropyltrimethoxysilane 2530-85-0, 3-Methacryloxypropyltrimethoxysilane 3179-31-5, 3MT 23779-32-0, N-(Triethoxysilylpropyl)urea
RL: MOA (Modifier or additive use); USES (Uses)
(adhesion promoter; polyimide based adhesive compns. useful in fabrication of curl-resistant laminate for electronic device and applied at moderate temperature)
IT 15541-60-3, Melamine pyrophosphate
RL: MOA (Modifier or additive use); USES (Uses)
(filler; polyimide based adhesive compns. useful in fabrication of curl-resistant laminate for electronic device and applied at moderate temperature)
IT 856045-04-0P
RL: IMF (Industrial manufacture); POF (Polymer in formulation); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(polyimide based adhesive compns. useful in fabrication of curl -resistant laminate for electronic device and applied at moderate temperature)
IT 218768-84-4, Melapur 200
RL: MOA (Modifier or additive use); USES (Uses)
(polyimide based adhesive compns. useful in fabrication of curl -resistant laminate for electronic device and applied at moderate temperature)
IT 108727-35-1, DEN 438EK85
RL: POF (Polymer in formulation); TEM (Technical or engineered material use); USES (Uses)
(polyimide based adhesive compns. useful in fabrication of curl -resistant laminate for electronic device and applied at moderate temperature)
IT 7440-50-8, Copper, miscellaneous 25036-53-7, Kapton
RL: MSC (Miscellaneous)
(substrate; polyimide based adhesive compns. useful in fabrication of curl-resistant laminate for electronic device and applied at moderate temperature)
RE.CNT 25 THERE ARE 25 CITED REFERENCES AVAILABLE FOR THIS RECORD
RE
(1) Anon; JP 04023879 1992 CAPLUS
(2) Anon; EP 0604038 A 1994 CAPLUS
(3) Anon; JP 10212468 1998 CAPLUS
(4) Anon; Database WPI, Section CH, Week 199429 1994
(5) Anon; Database WPI, Section CH, Week 200332 2003
(6) Anon; Definitions of plasticizer, Webster's Dictionary, Concise Oxford Dictionary
(7) Dueber; US 5536620 A 1996 CAPLUS
(8) Dueber; US 5643657 A 1997 CAPLUS
(9) Dueber; US 5728505 A 1998 CAPLUS
(10) Dueber; US 6218074 B1 2001 CAPLUS

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(12) Hiramoto; US 4243743 A 1981 CAPLUS
(13) Ishikawa; US 6117510 A 2000 CAPLUS
(14) Ishikawa; US 6468639 B2 2002 CAPLUS
(15) Jacobson; US 6015510 A 2000 CAPLUS
(16) Lynch; US 6274662 B1 2001 CAPLUS
(17) Masaki; US 5326792 A 1994 CAPLUS
(18) Rojstaczer; US 5935372 A 1999 CAPLUS
(19) Sugo; US 6538093 B2 2003 CAPLUS
(20) Tokuhisa; US 5916688 A 1999 CAPLUS
(21) Tsuji; US 6693162 B2 2004 CAPLUS
(22) Watanabe; US 4937133 A 1990 CAPLUS
(23) Yoshioka; US 6329050 B1 2001 CAPLUS
(24) Zhao; US 5859181 A 1999 CAPLUS
(25) Zhao; US 5942592 A 1999 CAPLUS

L16 ANSWER 5 OF 5 CAPLUS COPYRIGHT 2009 ACS on STN
AN 1995:896120 CAPLUS
DN 123:288272
OREF 123:51637a,51640a
ED Entered STN: 04 Nov 1995
TI Photocurable norbornene-based compositions for use in stereolithography
IN Steinmann, Bettina; Schulthess, Adrian; Wolf, Jean-Pierre; Hunziker, Max
PA Ciba-Geigy A.-G., Switz.
SO Ger. Offen., 16 pp.
CODEN: GWXXBX
DT Patent
LA German
IC ICM C08F020-20
ICS C08F020-36; C08F020-50; C08F020-38; G03F007-028; C08G063-91; C08G018-83; C08G063-672; C08G018-67; C09D133-14; C09D167-07; C09D175-16
ICA C09J004-02; C08G063-16; C08G063-40; C08G018-10; C08G018-48
CC 37-6 (Plastics Manufacture and Processing)
Section cross-reference(s): 74
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI DE 4440819	A1	19950524	DE 1994-4440819	19941115
PRAI CH 1993-3465	A	19931119		

CLASS

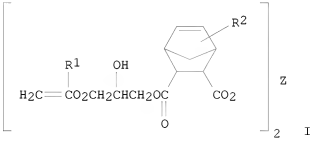
PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
DE 4440819	ICM	C08F020-20
	ICS	C08F020-36; C08F020-50; C08F020-38; G03F007-028; C08G063-91; C08G018-83; C08G063-672; C08G018-67; C09D133-14; C09D167-07; C09D175-16
	ICA	C09J004-02; C08G063-16; C08G063-40; C08G018-10; C08G018-48
	IPCI	C08F0020-20 [ICM,6]; C08F0020-36 [ICS,6]; C08F0020-50 [ICS,6]; C08F0020-38 [ICS,6]; C08F0020-00 [ICS,6,C*]; G03F0007-028 [ICS,6]; C08G0063-91 [ICS,6]; C08G0018-83 [ICS,6]; C08G0063-672 [ICS,6]; C08G0018-67 [ICS,6]; C09D0133-14 [ICS,6]; C09D0167-07 [ICS,6]; C09D0167-06 [ICS,6,C*]; C09D0175-16 [ICS,6]; C09D0175-14 [ICS,6,C*]; C09J0004-02 [ICA,6]; C08G0063-16 [ICA,6]; C08G0063-40 [ICA,6]; C08G0063-00 [ICA,6,C*];

C08G0018-10 [ICA,6]; C08G0018-48 [ICA,6]; C08G0018-00 [ICA,6,C*]

IPCR C08F0020-00 [I,C*]; C08F0020-30 [I,A]; C08G0018-00 [I,C*]; C08G0018-48 [I,A]; C08G0018-67 [I,A]; C08G0018-83 [I,A]; C08G0063-00 [I,C*]; C08G0063-676 [I,A]; C09D0167-06 [I,C*]; C09D0167-07 [I,A]; C09D0175-14 [I,C*]; C09D0175-16 [I,A]; G03F0007-00 [I,C*]; G03F0007-00 [I,A]; G03F0007-027 [I,C*]; G03F0007-027 [I,A]

ECLA C08F020/30; C08G018/48B; C08G018/67B2; C08G018/67B2+18/48; C08G018/83D2; C08G063/676; C09D167/07; C09D175/16; G03F007/00S; G03F007/027; G03F007/027H

GI



I

AB The title compns., with low curl factor, contain the di(meth)acrylates I (R1 = H, Me; R2 = H, alkyl, alkenyl; Z = bivalent aliphatic, cycloaliph., aromatic, or araliph. group or linking group of specified structure), polythiols, and photoinitiators. A mixture of I [R1 = H, R2 = Me, Z = (CH2)4] 76.1, pentaerythritol tetrakis(3-mercaptopropionate) 19.9, 1-benzoylcyclohexanol 3.85, and antioxidant 0.15 parts (viscosity 1.23 Pa-s at 30°) was cured by a He-Cd laser (40 mJ/cm2) to a preform [elastic modulus (Me) 4.6 N/mm2] which was completely cured by a UV-visible lamp to a molding with Me 754 N/mm2 and elongation 14.4%.

ST photocurable compn stereolithog; thiol polyhydric photocurable compn; pentaerythritol mercaptopropionate photocurable compn; norbornene deriv acrylate photocurable; methacrylate norbornene deriv photocurable

IT Thiols, uses
RL: TEM (Technical or engineered material use); USES (Uses)
(poly-, photocurable norbornene-based compns. for use in stereolithog.)

IT Urethane polymers, uses
RL: TEM (Technical or engineered material use); USES (Uses)
(polyoxyalkylene-, allyl group-terminated; photocurable norbornene-based compns. for use in stereolithog.)

IT Lithography
(stereo-, photocurable norbornene-based compns. for use in stereolithog.)

IT 9042-77-7D, allyl group-terminated 169909-01-7 169909-03-9 169970-65-4 170081-98-8 170082-01-6 170082-02-7 170082-03-8 170082-04-9

RL: TEM (Technical or engineered material use); USES (Uses)
(photocurable norbornene-based compns. for use in stereolithog.)

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COST IN U.S. DOLLARS	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	29.64	101.14

DISCOUNT AMOUNTS (FOR QUALIFYING ACCOUNTS)	SINCE FILE ENTRY	TOTAL SESSION
CA SUBSCRIBER PRICE	-5.74	-6.56

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